



Material Content Data Sheet



Sales Product Name		IPD06P003N		Issued		12. February 2019		
MA#		MA001782078						
Package		PG-TO252-3-313		Weight*		318.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.545	0.80	0.80	7995	7995
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.20	46.26	462188	462790
	non noble metal	aluminium	7429-90-5	1.168	0.37	0.37	3670	3670
wire	non noble metal	aluminium	7429-90-5	1.168	0.37	0.37	3670	3670
encapsulation	organic material	carbon black	1333-86-4	1.406	0.44		4418	
	plastics	epoxy resin	-	24.606	7.73		77315	
	inorganic material	silicondioxide	60676-86-0	114.595	36.01	44.18	360066	441799
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11751	11751
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4463	4474
solder	non noble metal	tin	7440-31-5	0.046	0.01		144	
	noble metal	silver	7440-22-4	0.057	0.02		180	
	non noble metal	lead	7439-92-1	2.184	0.69	0.72	6862	7186
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60257	60335
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com